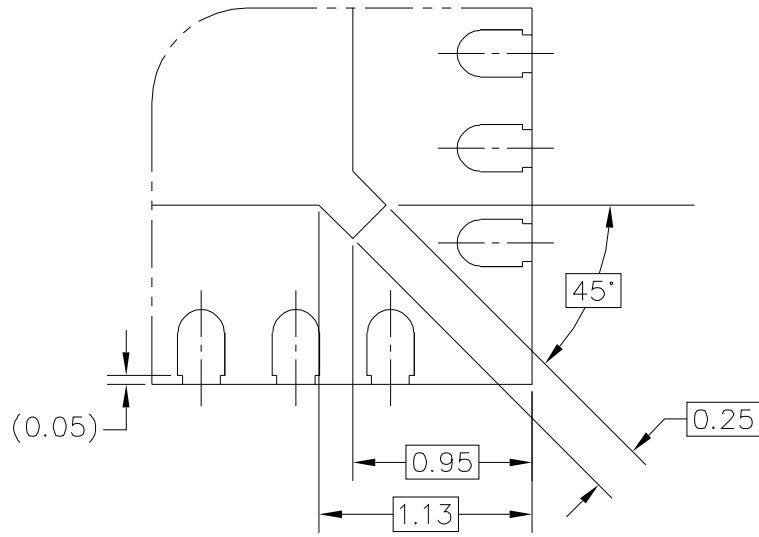
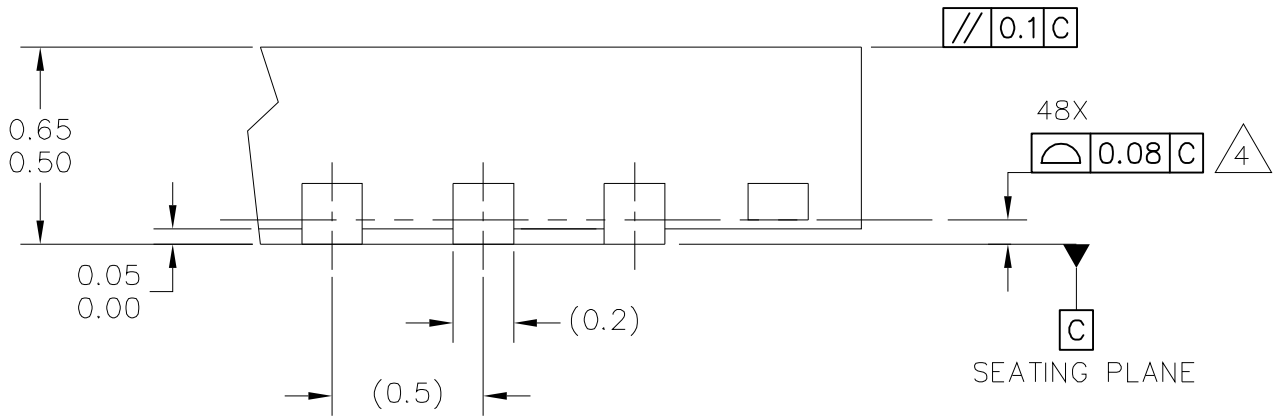


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TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 0.58, 0.5 PITCH, 48 TERMINAL	DOCUMENT NO: 98ASA00616D REV: A STANDARD: NON-JEDEC SOT1586-1 13 JAN 2016	



DETAIL F




DETAIL G
VIEW ROTATED 90°CW

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TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 0.58, 0.5 PITCH, 48 TERMINAL	DOCUMENT NO: 98ASA00616D	REV: A
	STANDARD: NON-JEDEC	
	SOT1586-1	13 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 0.58, 0.5 PITCH, 48 TERMINAL		DOCUMENT NO: 98ASA00616D	REV: A
		STANDARD: NON-JEDEC	
		SOT1586-1	13 JAN 2016